

Title (en)

RESIST COMPOSITION AND PATTERN FORMING METHOD USING THE SAME

Title (de)

RESISTZUSAMMENSETZUNG UND VERFAHREN ZUR STRUKTURFORMUNG DAMIT

Title (fr)

COMPOSITION DE RESERVE ET PROCEDE L'UTILISANT POUR FORMER UN MOTIF

Publication

**EP 2252915 A1 20101124 (EN)**

Application

**EP 09720706 A 20090313**

Priority

- JP 2009055543 W 20090313
- JP 2008066746 A 20080314

Abstract (en)

[origin: WO2009113735A1] A resist composition and a pattern forming method using the composition are provided, the resist composition including: (A) a resin that decomposes by an action of an acid to increase a solubility of the resin (A) in an alkali developer; (B) a compound capable of generating an acid upon irradiation with actinic rays or radiation; (C) a compound represented by formula (C1); and (D) a solvent: wherein n represents an integer of 1 to 6; w represents an integer of 1 to 6; p represents an integer of 1 to 6; m represents an integer of 1 to 6; Ra, Rb, Rc and Rd each independently represents a hydrogen atom, an alkyl group, a cycloalkyl group, an aryl group or an aralkyl group, provided that Ra and Rb may combine together to form a ring, and Rc and Rd may combine together to form a ring.

IPC 8 full level

**G03F 7/004** (2006.01); **C08F 12/04** (2006.01); **C08F 20/10** (2006.01); **G03F 7/039** (2006.01); **H01L 21/027** (2006.01)

CPC (source: EP KR US)

**C08F 8/12** (2013.01 - EP US); **C08F 12/24** (2013.01 - US); **C08F 212/24** (2020.02 - EP US); **C09D 125/14** (2013.01 - EP US); **G03F 7/004** (2013.01 - KR); **G03F 7/0045** (2013.01 - EP KR US); **G03F 7/0046** (2013.01 - KR); **G03F 7/0047** (2013.01 - KR); **G03F 7/039** (2013.01 - KR); **G03F 7/0392** (2013.01 - EP KR US); **G03F 7/0397** (2013.01 - EP KR US); **H01L 21/027** (2013.01 - KR); **H01L 21/0271** (2013.01 - KR); **G03F 7/0046** (2013.01 - EP US)

Designated contracting state (EPC)

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Designated extension state (EPC)

AL BA RS

DOCDB simple family (publication)

**WO 2009113735 A1 20090917**; EP 2252915 A1 20101124; EP 2252915 A4 20121017; JP 2009222939 A 20091001; JP 4703674 B2 20110615; KR 20100125320 A 20101130; TW 200941142 A 20091001; TW I438572 B 20140521; US 2011014570 A1 20110120; US 8785104 B2 20140722

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**JP 2009055543 W 20090313**; EP 09720706 A 20090313; JP 2008066746 A 20080314; KR 20107020574 A 20090313; TW 98108115 A 20090313; US 92135409 A 20090313